

10 9 8 7 6 5 4 3 2 1

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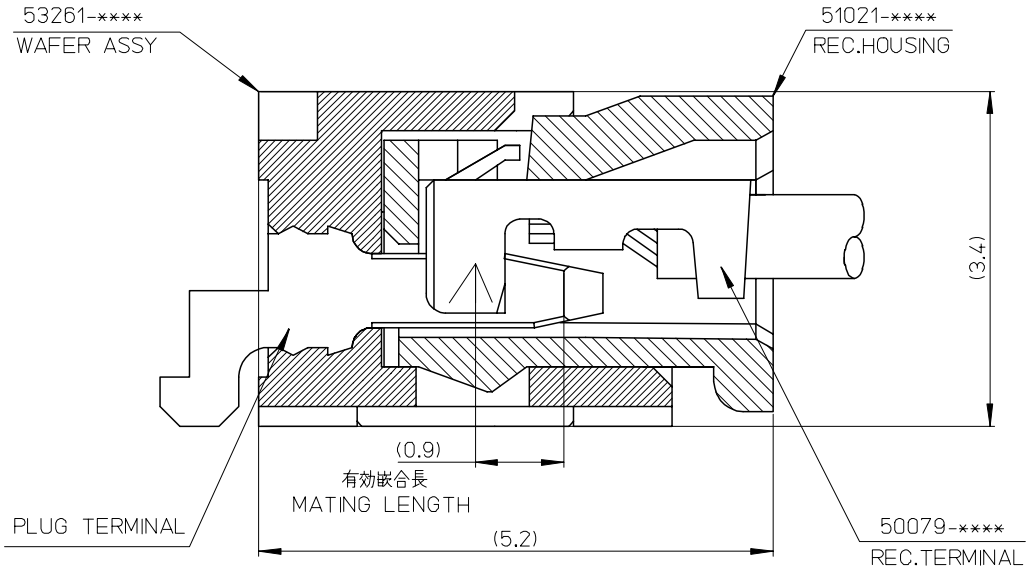
C

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A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART			
	ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-51021-002		SHEET NO. 1 OF 1	

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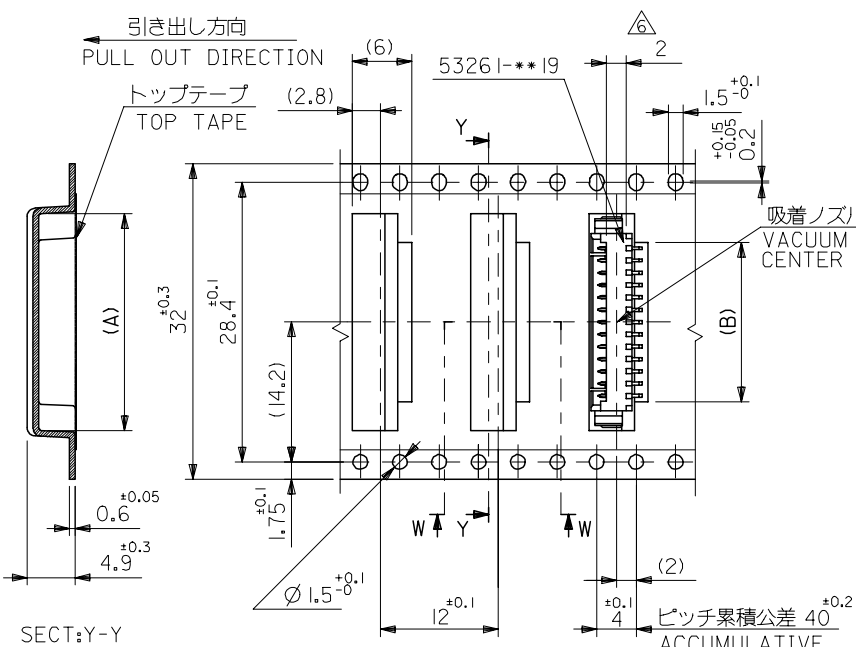
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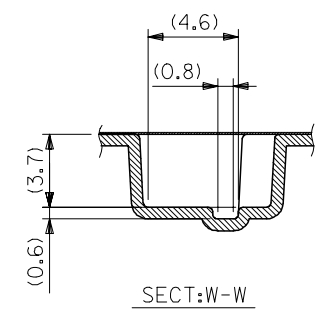
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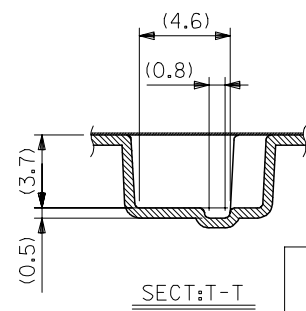




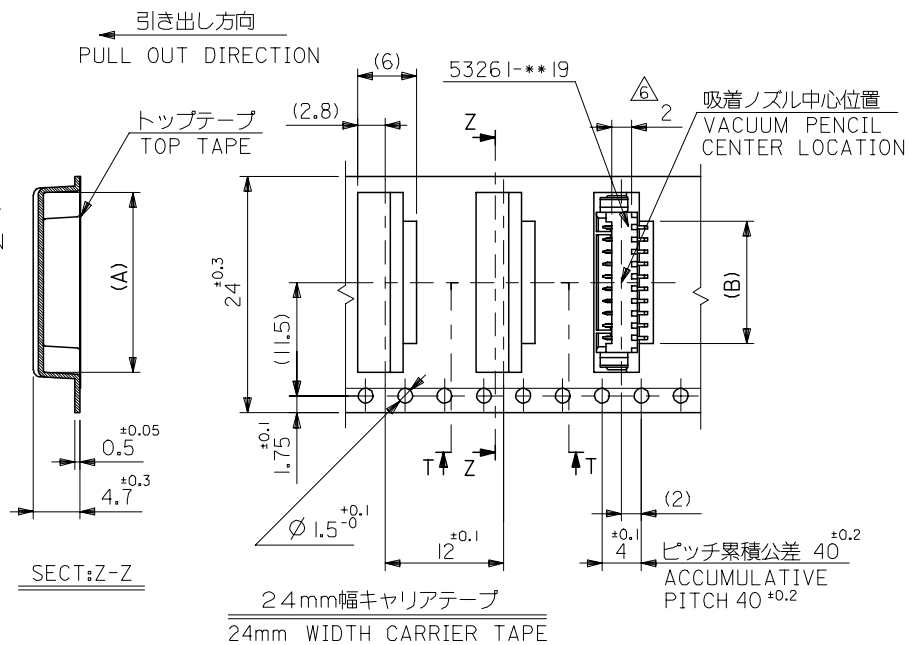
32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE



SECT:W-W



SECT:T-T



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
24	29.4	25.4	12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL. NO.	種数 CKT.
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE '04/02/06		MOLEX INCORPORATED		
30 OVER	±0.3	APPROVED BY M. SASAO		DATE '04/02/06				
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SEE CHART		SD-53261-023		2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

10 9 8 7 6 5 4 3 2 1

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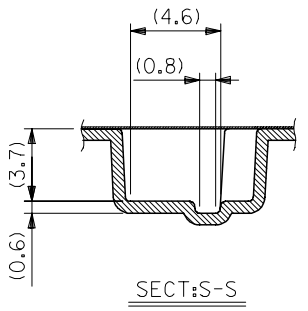
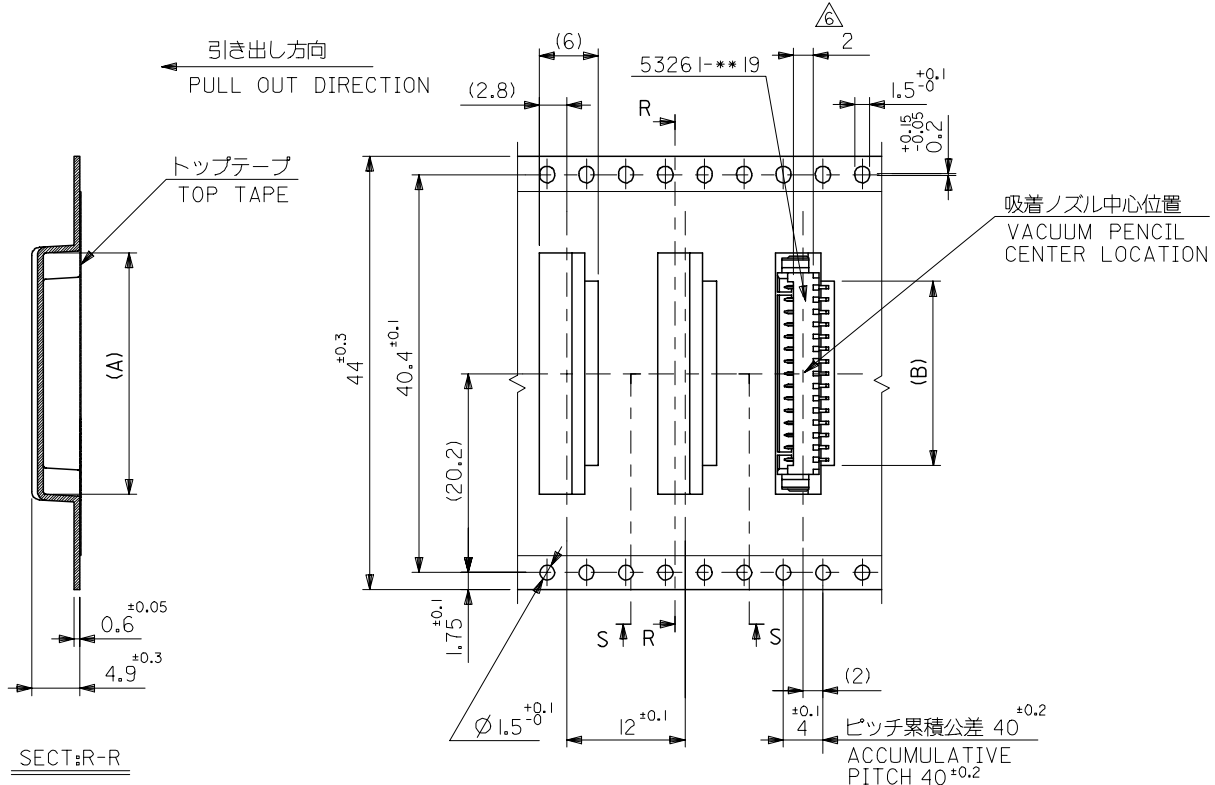
E

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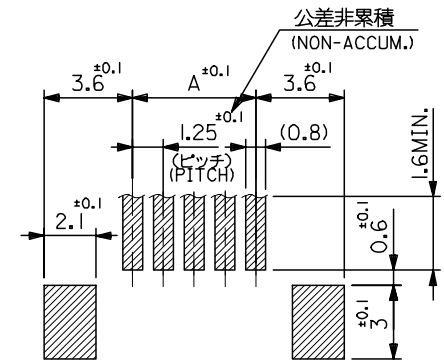
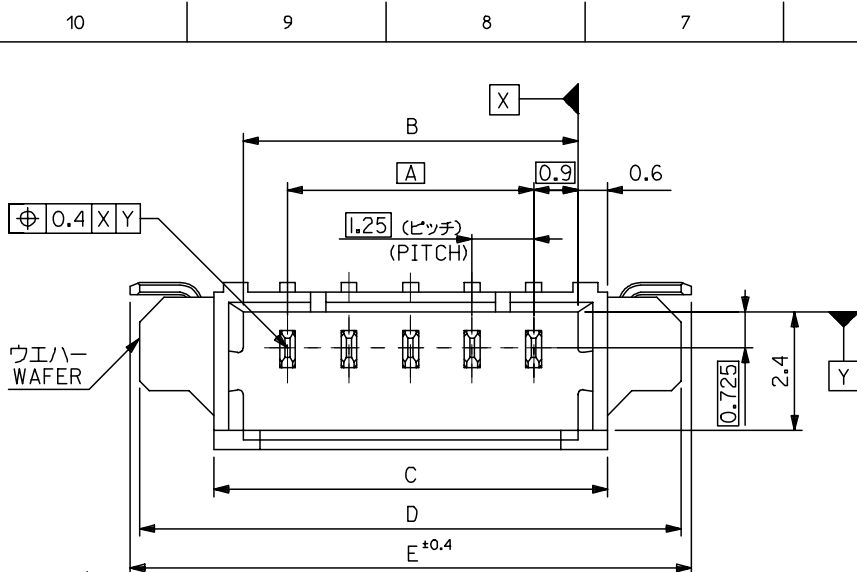
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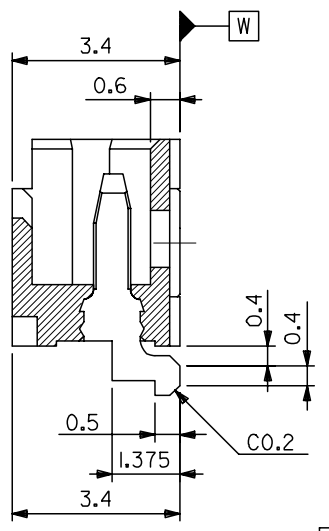
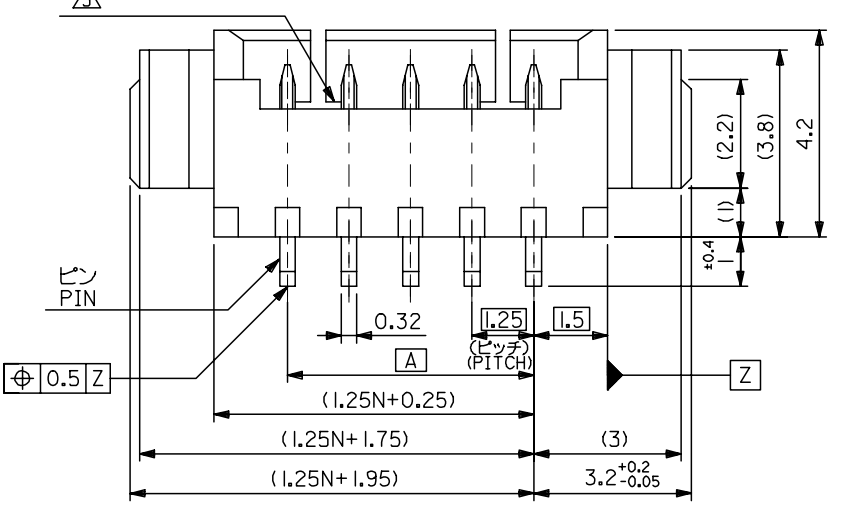


44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

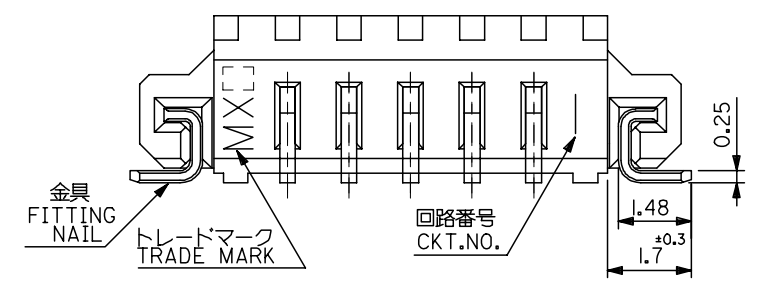
REVISED	EC NO: J2008-0056	DRWN:KSAIT001	2007/07/31	CHKD:THARUYAMA	2007/07/31	APPR:NUKITA	2007/08/10	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	MODEL NO.	53261-***71	44	49.4	45.4	18.7	24.5	53261-1571	15		
B	REV							10 UNDER	±0.2	DIMENSION STYLE		D	C	B	A	MATERIAL. NO.		極致		
									10 OVER 30 UNDER	±0.25	MM ONLY		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION			
									30 OVER	±0.3	DRAWN BY DATE		TITLE		METRIC					
									ANGULAR	±3 °	H. SHIMABUKUR '04/02/06		1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG							
									DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY DATE		MOLEX MOLEX INCORPORATED							
											K. TOJO '04/02/06		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
											M. SASAO '04/02/06		SEE CHART		SD-53261-023		3 OF 3			
											MATERIAL NO.									
											SIZE									
											A3									
											THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)  
(SCALE 5:1)



[断面図]  
[CROSS SECTION]



注記 NOTES

1. 嵌合相手: 51021 シリウス  
MATES WITH: 51021 SERIES
2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
PIN: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM  
金具  
FITTING NAIL: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
- △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。  
LOCKING WINDOW:  
ONE PLACE FOR 2 AND 3 CKT. AND  
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX、下方向に0.1 MAXとする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

MODEL NO.	E	D	C	B	A	MATERIAL. NO.	極数 CKT.
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REVISED EC NO: J2005-3130 DRW:NAIDA 2005/04/19 CHK:KTOYODA 2005/04/21 APP:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024			
	ANGULAR	±3 °	MATERIAL NO. SEE DRAWING		SHEET NO. 1 OF 1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	